



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB76NF75	T2D2*ED7HA62	A	3068	2017-01-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-9.15-4.5	2	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T2D2*ED7HA62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	15.201	mg	supplier	die	Silicon (Si)	7440-21-3		14.694	mg	966647	10648
				supplier	metallization	Aluminium (Al)	7429-90-5		0.286	mg	18815	207
				supplier	Passivation	Silicon Oxide	7631-86-9		0.079	mg	5197	57
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	460	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.100	mg	6579	72
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.035	mg	2302	25
Leadframe	Copper & its alloys	778.631	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.536	mg	998594	563432
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	460	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	840	474
				supplier	metallization	Nickel (Ni)	7440-02-0		0.077	mg	98	56
				supplier	metallization	Phosphorus (P)	7723-14-0		0.006	mg	8	4
Soft solder	Solder	13.626	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	13.012	mg	954939	9429
				supplier	solder	Silver (Ag)	7440-22-4		0.341	mg	25026	247
				supplier	solder	Tin (Sn)	7440-31-5		0.273	mg	20035	198
Bonding wires	Other inorganic materials	1.710	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.703	mg	995906	1234
				supplier	wire	Magnesium (Mg)	7439-95-4		0.007	mg	4094	6
Encapsulation	Other Organic Materials	568.343	mg	supplier	mold compound	Silica, vitreous	60676-86-0		458.084	mg	805999	331945
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		39.784	mg	70000	28829
				supplier	mold compound	Phenol resin	9003-35-4		22.734	mg	40000	16474
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		34.101	mg	60001	24711
				supplier	mold compound	Antimony Trioxide	1309-64-4		6.820	mg	12000	4942
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		3.978	mg	6999	2883
Connections coating	Solder	2.489	mg	supplier	mold compound	Carbon black	1333-86-4		2.842	mg	5001	2059
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804